

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE



Applicant: Wayne Glenn Renken  
Title: System and Method for Heating and Cooling Wafer at Accelerated Rates  
Application No.: 10/619,731 Filing Date: July 15, 2003  
Examiner: Unknown Group Art Unit: 1725  
Docket No.: SENS.007US1 Conf. No.: 7022

Certificate of Mailing Under 37 CFR 1.8

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Mary E. Buogin  
Signature

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Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**PRELIMINARY AMENDMENT**

Dear Sir:

Please amend the above-identified application as follows:

**Amendments to the Specification** begin on page 2 of this paper.

**Remarks** begin on page 3 of this paper.